

ABSTRACT OF THE DISCLOSURE

5 [Since] Die pads 50, 51, an external connecting electrode 52 and a bridge are covered with an insulating resin after half-etching, [they are] formed into a single package without [using] a coupling member such as a supporting lead or adhesive tape. In addition, since no supporting board is required, a low-profile[d] semiconductor device with [excellent] improved heat radiation can be [realized] provided.